

BL672

mATX chassis

Features

● New Partition Plate Cooling Technology (PPCT)

PPCT is the world's first advanced thermal and acoustic cooling technology. It provides SFF chassis excellent thermal solutions while creating a quieter computing experience. The second generation of PPCT includes a removable air duct and an enlarged adjustable vent for various positions within your PC. The New Partition Plate Cooling Technology also supports the LGA1156 socket.



● Detachable Drive Cage

For easy installation.



● Tool Free

Optional screwless designs-ODD/FDD/HDD bays, expansion slots, and top cover.



High Compatibility

It is compatible with standard desktop components, which makes the installation easier and provides a great expandability when needed.

Design Philosophy

A small 11.5L SFF chassis with optimal thermal and acoustic performance without additional system fan.

Multi-Enjoyment

Designated Infrared Receiver position to support Media Center and optional Internal amplifier.

CASE SIZE	S.F.F Slim Chassis
PROCESSOR	Support Dual Core and Quad Core Processor
EXTERNAL DRIVE BAY	5.25" x 1, 3.5" x 1
INTERNAL DRIVE BAY	3.5" x 2
FRONT PORTS	USB 2.0 x 4, HD Audio
DIMENSIONS (HxWxD)	13" x 3.8" x 14.4"
w/o Front Panel	330 x 96 x 365 mm (11.5L)
M/B	Micro ATX
I/O EXPANSION SLOTS	Low Profile Slot x 4
POWER SUPPLY	Standard TFX 12V
THERMAL SOLUTION	Removable air filter, 80mm side fan
SAFETY	Meets RoHS, CE and FCC Class B Requirements
SECURITY	Padlock Loop / Kensington Slot
OPTIONAL	<ul style="list-style-type: none"> • Intel Lanyu Ref. Design-New Partition Plate Cooling Tech (New PPCT) • IR / IEEE 1394 / Chassis Intrusion Switch • Tool-Free ODD/FDD/HDD Bays Clips • Tool-Free Expansion Slots Clip • Tool-Free Top Cover Clips

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Specification